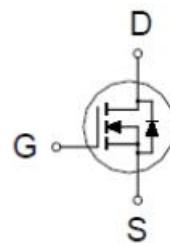
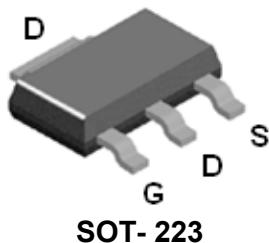


# P0120HLB

## N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
200V	1.4Ω @ $V_{GS} = 10V$	0.8A



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current	$I_D$	0.8	A
		0.7	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	3.5	
Avalanche Current	$I_{AS}$	2.6	
Avalanche Energy	$E_{AS}$	3.4	mJ
Power Dissipation	$P_D$	2.4	W
		1.5	
Operating Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		53	°C / W

<sup>1</sup>Pulse width limited by maximum junction temperature.

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## N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	200			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	2.2	3	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 200\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}} = 160\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			10	
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 0.5\text{A}$		1.5	1.9	$\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 0.5\text{A}$		1.2	1.4	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 10\text{V}, I_D = 0.5\text{A}$		1.2		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		94		pF
Output Capacitance	$C_{\text{oss}}$			30		
Reverse Transfer Capacitance	$C_{\text{rss}}$			8		
Total Gate Charge <sup>2</sup>	$Q_{\text{g(VGS=10V)}}$	$V_{\text{DS}} = 160\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 0.8\text{A}$		3.7		nC
	$Q_{\text{g(VGS=4.5V)}}$			1.7		
Gate-Source Charge <sup>2</sup>	$Q_{\text{gs}}$			1.2		
Gate-Drain Charge <sup>2</sup>	$Q_{\text{gd}}$			1.4		
Turn-On Delay Time <sup>2</sup>	$t_{\text{d(on)}}$	$V_{\text{DS}} = 100\text{V}, I_D \approx 0.8\text{A}$ $V_{\text{GS}} = 10\text{V}, R_{\text{GS}} = 6\Omega$		5		nS
Rise Time <sup>2</sup>	$t_r$			16		
Turn-Off Delay Time <sup>2</sup>	$t_{\text{d(off)}}$			8		
Fall Time <sup>2</sup>	$t_f$			18		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_S$				0.8	A
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = 0.8\text{A}, V_{\text{GS}} = 0\text{V}$			1	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 0.8\text{A}, dI/dt = 100\text{A} / \mu\text{s}$		68		nS
Reverse Recovery Charge	$Q_{\text{rr}}$			118		nC

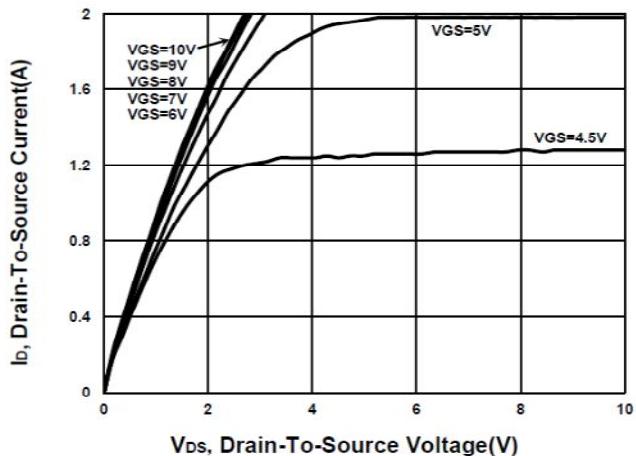
<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

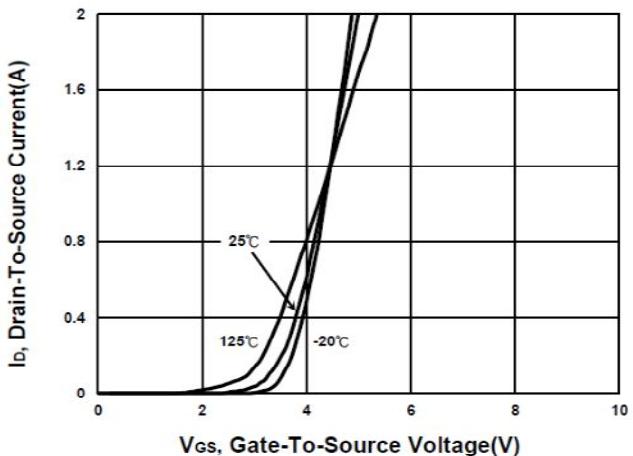
## P0120HLB

### N-Channel Enhancement Mode MOSFET

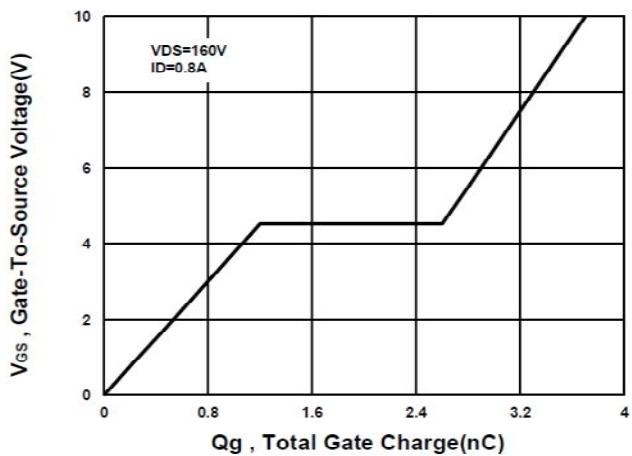
**Output Characteristics**



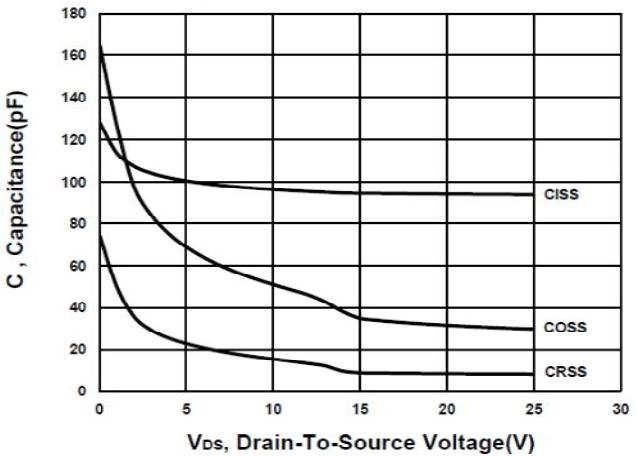
**Transfer Characteristics**



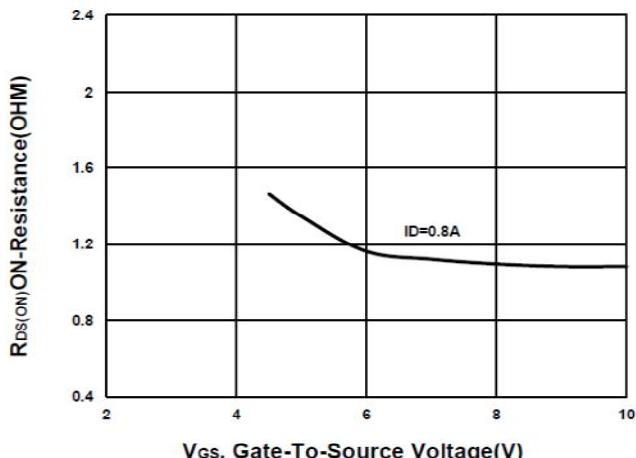
**Gate charge Characteristics**



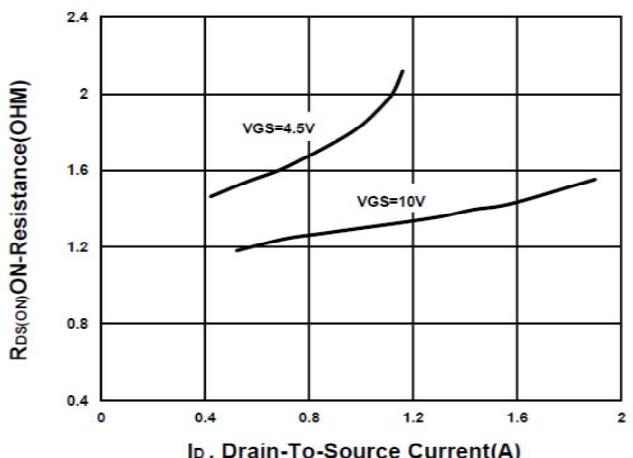
**Capacitance Characteristic**



**On-Resistance VS Gate-To-Source**

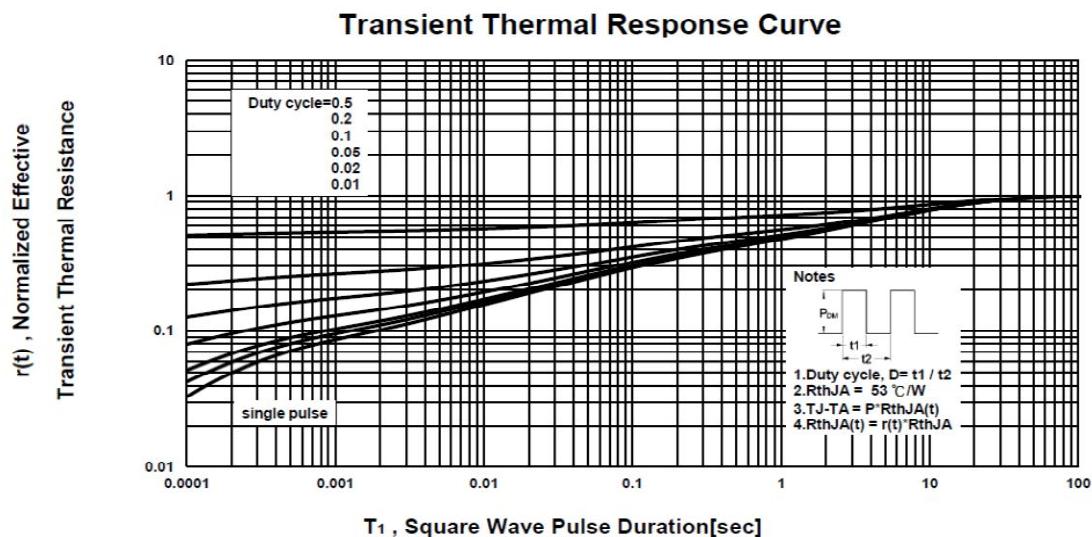
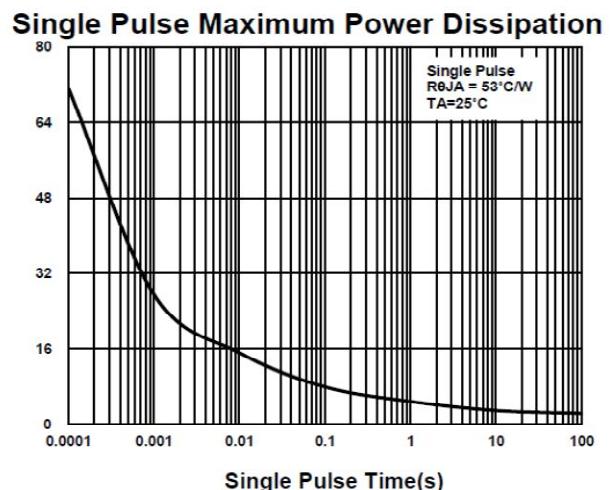
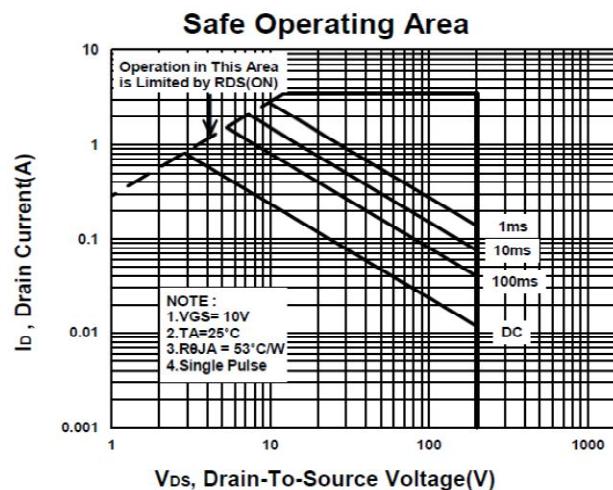
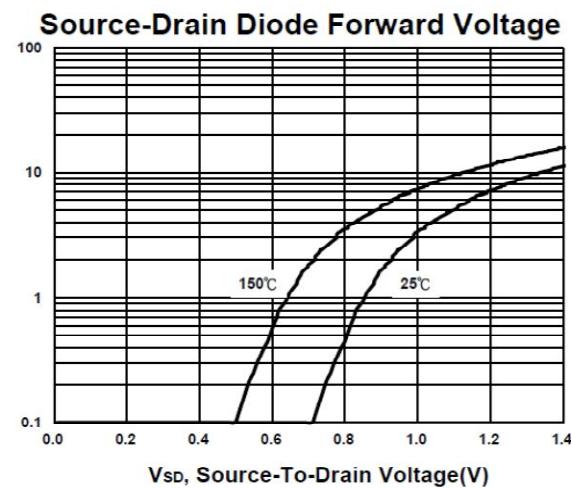
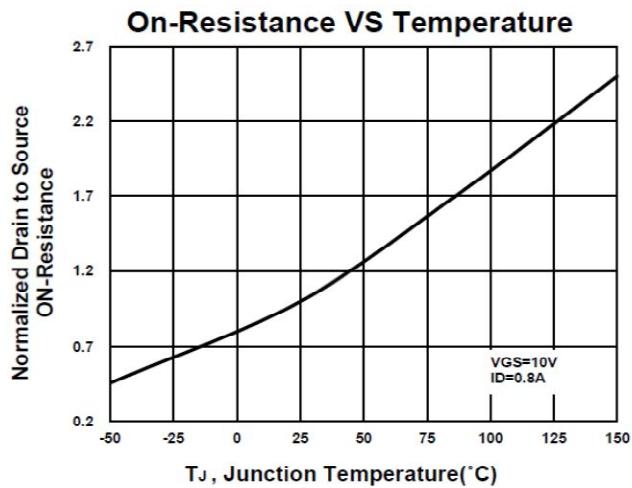


**On-Resistance VS Drain Current**



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## N-Channel Enhancement Mode MOSFET

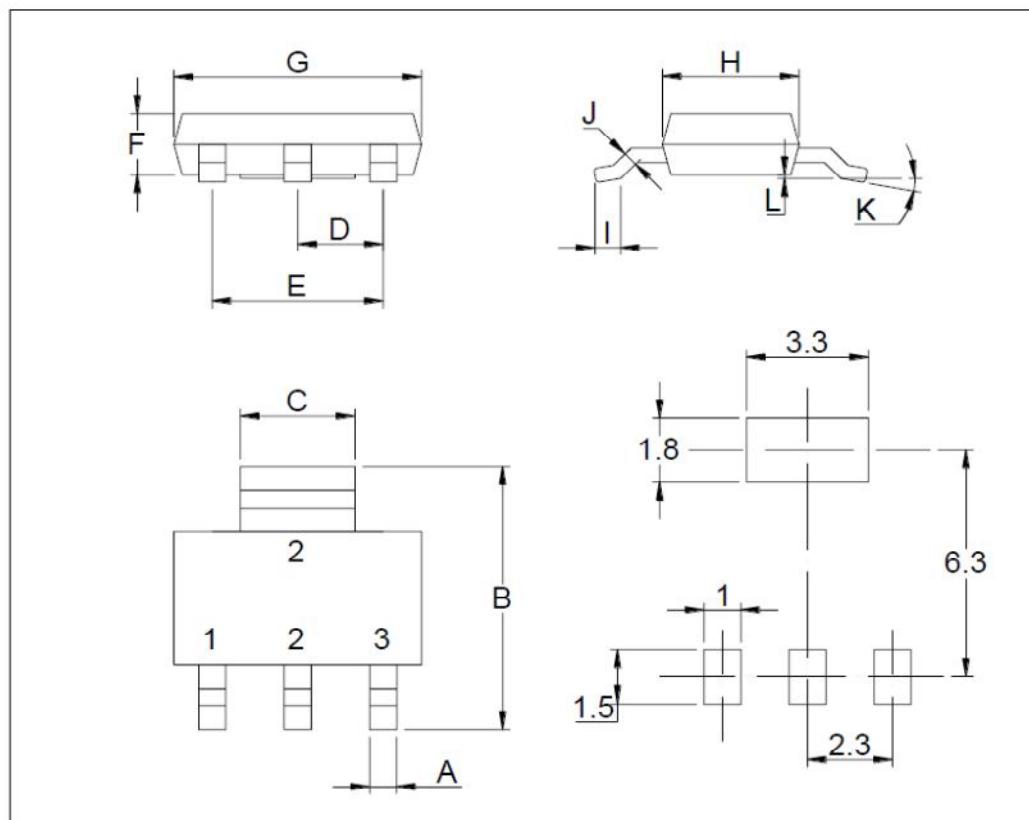


# P0120HLB

## N-Channel Enhancement Mode MOSFET

### SOT-223 MECHANICAL DATA

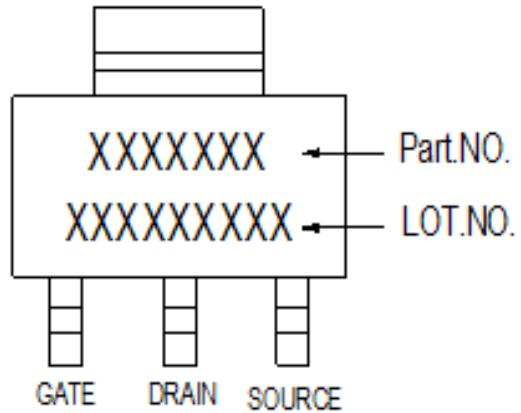
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.60	0.76	0.84	H	3.30	3.50	3.70
B	6.70	7.00	7.30	I	0.50	1.00	1.20
C	2.85	3.00	3.10	J	0.23	0.3	0.4
D	2.25	2.30	2.35	K	0°		10°
E	4.35	4.60	4.85	L	0	0.1	0.2
F	1.40	1.60	1.80	M			
G	6.30	6.50	6.80	N			



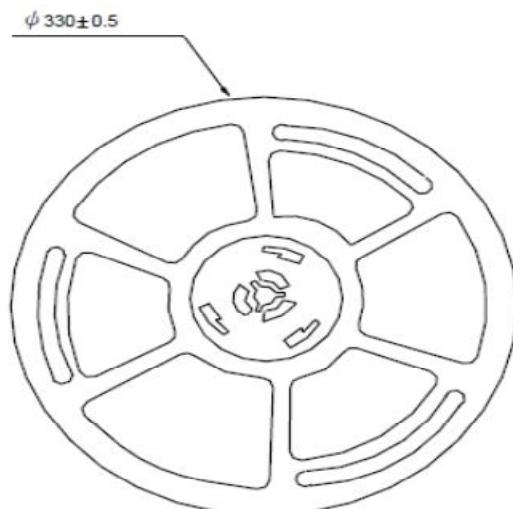
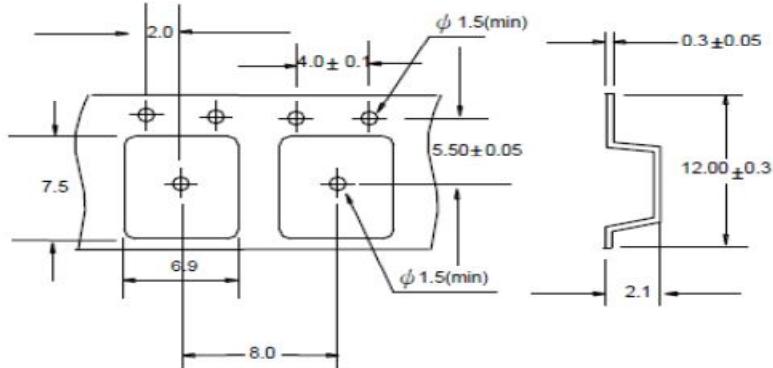
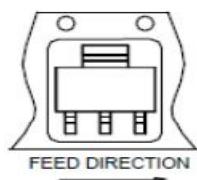
## P0120HLB

### N-Channel Enhancement Mode MOSFET

#### A. Marking Information



#### B. Tape&Reel Information: 2500pcs/Reel

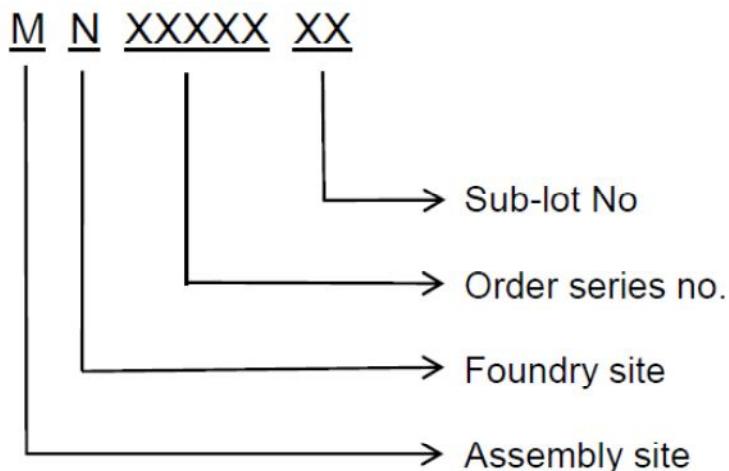


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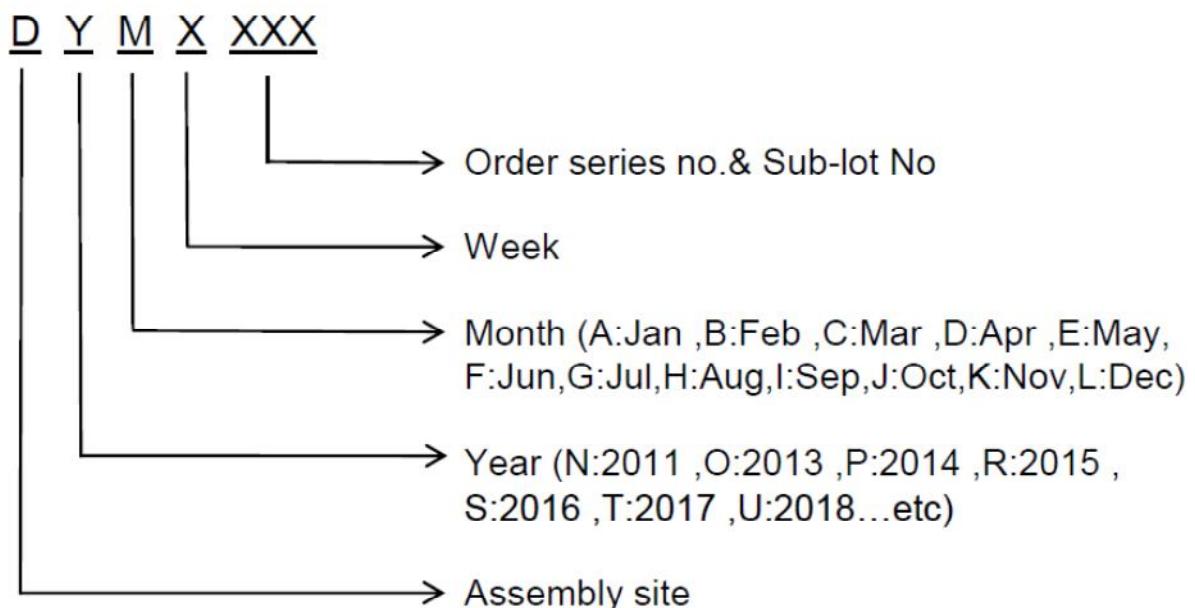
### N-Channel Enhancement Mode MOSFET

#### C. Lot No.&Date Code rule

##### 1. Lot No.



##### 2. Date Code



**P0120HLB****N-Channel Enhancement Mode MOSFET****D.Label rule**

标签内容(Label content)



1	Label Size	30 * 90 mm	
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)	
3	U-NIKC	Height: 4 mm	
4	Package	Height: 2 mm	
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12	
6	Device	Height: 3 mm (Max: 16 Digit)	
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot	
8	D/C	Height: 3 mm (Max: 7 Digit)	
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed	
10	RoHS label	<b>RoHS</b> long axis: 12 mm      minor axis: 6 mm bottom color: White Font color: Black      Font style: Arial	
11	Halogen Free label	<b>G</b> Diameter: 10 mm      bottom color: Green Font color: Black      Font style: Arial	
12	Scan information	Device / Lot / D/C / QTY , Insert “ / “ between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least	